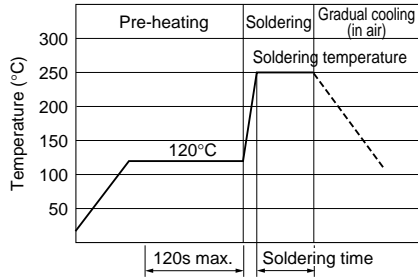


1. Soldering Conditions

(1) Flux, Solder

- Rosin-based flux should be used. Do not use strong acidic flux with halide content exceeding 0.2wt% (chlorine conversion value)
- Use Sn-3.0Ag-0.5Cu solder

(2) Flow soldering profile



Standard profile		Limit profile		
Sn-3.0Ag-0.5Cu solder				
Soldering temp.	Soldering time	Soldering temp.	Soldering time	Cycle of flow
250±2°C	4-6s	265±3°C	5s	2 times

For additional mounting methods, please contact Murata.

2. Cleaning

Avoid cleaning the product due to non-waterproof construction.

3. Storage and Handling Requirements

(1) Storage period

Product should be used within 12 months after receiving. Solderability should be checked if this period is exceeded.

(2) Storage conditions

Storage Temperature: -10 to 40 °C

Relative humidity: 30 to 70%

Avoid sudden changes in temperature and humidity.

Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, as it may cause oxidation of lead terminals resulting in poor solderability or corrosion of component windings.

(3) Handling conditions

Care should be taken when transporting or handling the product to avoid excessive vibration or mechanical shock.